

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

5 **Listing of Claims:**

Claims 1-35 (canceled)

Claim 36 (currently amended): A fuse structure comprising:

- a substrate, a fuse area being included on a surface of the substrate;
- 10 a first dielectric layer on the surface of the substrate;
- at least one metal structure disposed in the first dielectric layer;
- a second dielectric layer disposed on the first dielectric layer and the metal structure;
- at least one fuse on the second dielectric layer in the fuse area, the fuse having a thin portion and a thick portion;
- 15 ~~at least one~~ a plurality of conductive plugs disposed in the second dielectric layer for connecting the fuse and the metal structure;
- a third dielectric layer on the second dielectric layer that covers the thick portion;
- and
- a first opening in the third dielectric layer exposing the thin portion; and
- 20 a fourth dielectric layer on the third dielectric layer that covers the thin portion of the
fuse.

Claim 37 (original): The fuse structure of claim 36 wherein a ratio of a thickness of the thick portion to a thickness of the thin portion is approximately 1 to 8.

- 25 Claim 38 (original): The fuse structure of claim 36 wherein a thickness of the thick portion is approximately 0.8 to 1.6 μ m, and a thickness of the thin portion is smaller than 0.8 μ m.

Claim 39 (currently amended): The fuse structure of claim 36 further comprising:
at least one bonding pad on the second dielectric layer in a bonding pad area; and
a second opening in the third dielectric layer exposing the bonding pad; and
5 ~~a fourth dielectric layer on the third dielectric layer that covers the thin portion.~~

Claim 40 (currently amended): The fuse structure of claim ~~39~~36 wherein the fourth dielectric layer is a PE-oxide layer.

10 Claim 41 (canceled)

Claim 42 (previously presented): The fuse structure of claim 36 wherein the metal structure is copper (Cu).

15 Claim 43 (previously presented): The fuse structure of claim 36 wherein the first dielectric layer is a low-k dielectric layer.

Claim 44 (previously presented): The fuse structure of claim 36 wherein the metal structure is copper, and the first dielectric layer is a low-k dielectric layer.

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Claim 45 (original): The fuse structure of claim 44 wherein a dielectric constant of the low-k dielectric layer is approximately 2.0 to 3.5.

25 Claim 46 (original): The fuse structure of claim 44 wherein the low-k dielectric layer comprises a carbon-contained oxide layer or an inorganic dielectric material layer.

Claims 47-60 (canceled)

Appl. No. 10/711,790
Amdt. dated July 06, 2007
Reply to Office action of April 18, 2007

Claim 61 (previously presented): The fuse structure of claim 36 wherein the thick portion and the thin portion of the fuse comprise same material.

Claim 62 (canceled)